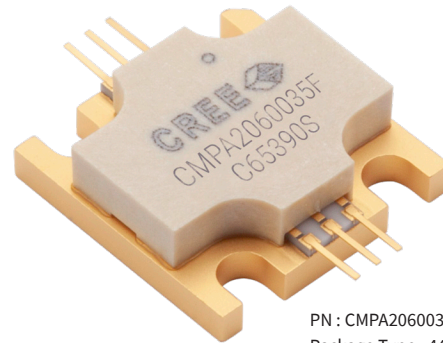


CMPA2060035F

35 W, 2.0 - 6.0 GHz, GaN MMIC Power Amplifier

Description

Wolfspeed's CMPA2060035F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity and higher thermal conductivity. GaN HEMTs also offer greater power density and wider bandwidths compared to Si and GaAs transistors. This MMIC contains a two-stage reactively matched amplifier enabling very wide bandwidths to be achieved in a small footprint screw-down package featuring a Copper-Tungsten heat-sink.



PN : CMPA2060035F
Package Type : 440219

Features

- 28 dB Small Signal Gain
- 35 W Typical P_{SAT}
- Operation up to 28 V
- High Breakdown Voltage
- High Temperature Operation

Applications

- Ultra Broadband Amplifiers
- Fiber Drivers
- Test Instrumentation
- EMC Amplifier Drivers

Typical Performance Over 2.0-6.0 GHz, 28 V ($T_c = 25^\circ\text{C}$)

| Parameter | 2.0 GHz | 4.0 GHz | 6.0 GHz | Units |
|-------------------------------------|---------|---------|---------|-------|
| Small Signal Gain | 24.8 | 26.5 | 25.0 | dB |
| Output Power ¹ | 30.0 | 44.7 | 32.5 | W |
| Power Gain ¹ | 17.7 | 19.5 | 18.1 | dB |
| Power Added Efficiency ¹ | 43 | 47 | 36 | % |

Notes:

¹ $V_{DD} = 28\text{ V}$, $I_{DQ} = 1.2\text{ A}$, $P_{IN} = 27\text{ dBm}$. All data tested CW



Absolute Maximum Ratings (not simultaneous) at 25 °C

| Parameter | Symbol | Rating | Units | Conditions |
|--------------------------------------|-----------------|-----------|-------|------------------------------|
| Drain-source Voltage | V_{DS} | 84 | VDC | |
| Gate-source Voltage | V_{GS} | -10, +2 | VDC | |
| Storage Temperature | T_{STG} | -65, +150 | °C | |
| Operating Junction Temperature | T_J | 225 | °C | |
| Forward Gate Current | I_G | 16 | mA | |
| Screw Torque | T | 40 | in-oz | |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 2.06 | °C/W | 85 °C, $P_{DISS} = 65$ W, CW |
| Case Operating Temperature | T_C | -40, +150 | °C | |

Electrical Characteristics (Frequency = 2.0 GHz to 6.0 GHz unless otherwise stated; $T_C = 25$ °C)

| Characteristics | Symbol | Min. | Typ. | Max. | Units | Conditions |
|---|--------------|------|-------|-------|----------|--|
| DC Characteristics^{1,2} | | | | | | |
| Gate Threshold Voltage | $V_{(GS)TH}$ | -3.4 | -3.0 | -2.7 | V | $V_{DS} = 10$ V, $I_D = 16.5$ mA |
| Gate Quiescent Voltage | $V_{(GS)Q}$ | - | -2.6 | - | V_{DC} | $V_{DD} = 28$ V, $I_D = 1.2$ A |
| Saturated Drain Current ¹ | I_{DS} | 11.9 | 16.5 | - | A | $V_{DS} = 6.0$ V, $V_{GS} = 2.0$ V |
| Drain-Source Breakdown Voltage | V_{BD} | 84 | - | - | V | $V_{GS} = -8$ V, $I_D = 16.5$ mA |
| RF Characteristics^{3,4,5} | | | | | | |
| Small Signal Gain | S21 | 22.2 | 26.5 | - | dB | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Frequency = 2.0 - 6.0 GHz |
| Input Return Loss | S11 | - | -11 | -4 | dB | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Frequency = 2.0 - 6.0 GHz |
| Output Return Loss | S22 | - | -11.6 | -4 | dB | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Frequency = 2.0 - 6.0 GHz |
| Output Power ₁ | P_{OUT} | 23.7 | 30.0 | - | W | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Freq = 2.0 GHz |
| Output Power ₂ | P_{OUT} | 34.3 | 44.7 | - | W | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Freq = 4.0 GHz |
| Output Power ₃ | P_{OUT} | 23.7 | 32.5 | - | W | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Freq = 6.0 GHz |
| Power Added Efficiency ₁ | PAE | 34.5 | 43 | - | % | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Freq = 2.0 GHz |
| Power Added Efficiency ₂ | PAE | 37 | 47 | - | % | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Freq = 4.0 GHz |
| Power Added Efficiency ₃ | PAE | 23 | 36 | - | % | $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, Freq = 6.0 GHz |
| Output Mismatch Stress | VSWR | - | - | 5 : 1 | Ψ | No damage at all phase angles, $V_{DD} = 28$ V, $I_{DQ} = 1.2$ A, $P_{IN} = 27$ dBm |

Notes:

¹ Measured on-wafer prior to packaging

² Scaled from PCM data

³ Measured in CMPA2060035F-AMP

⁴ Measured at $P_{IN} = 27$ dBm

⁵ Tested CW



Typical Performance

Figure 1. CMPA2060035F S21 vs. Frequency

$I_{DQ} = 1.2 \text{ A}$

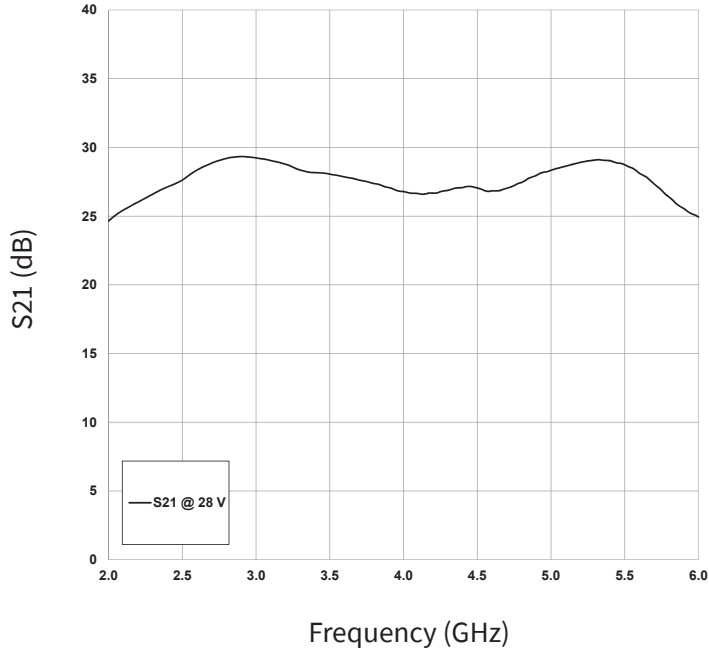
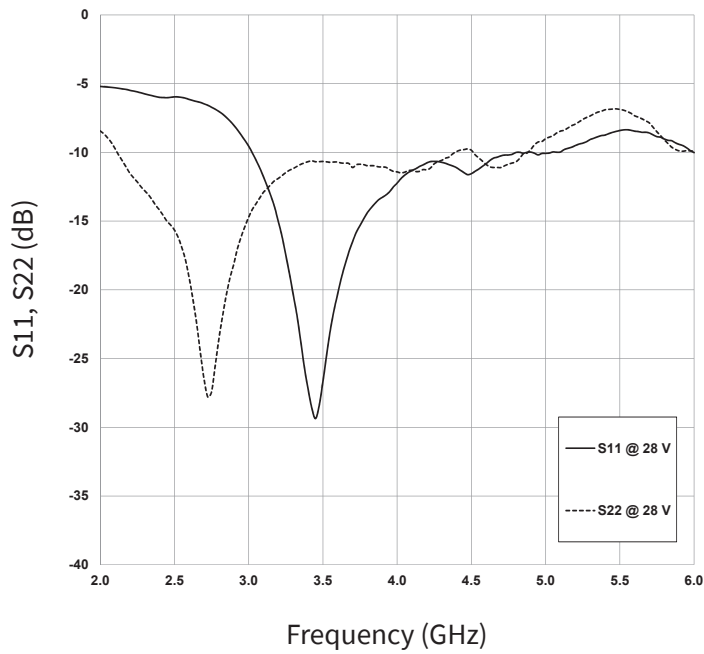


Figure 2. CMPA2060035F Return Losses vs. Frequency

$I_{DQ} = 1.2 \text{ A}$





Typical Performance

Figure 3. CPA2060035F Output Power and Power Added Efficiency vs. Frequency

$I_{DQ} = 1.2$ A, Case Temperature = 25 °C, Power Input = 27 dBm

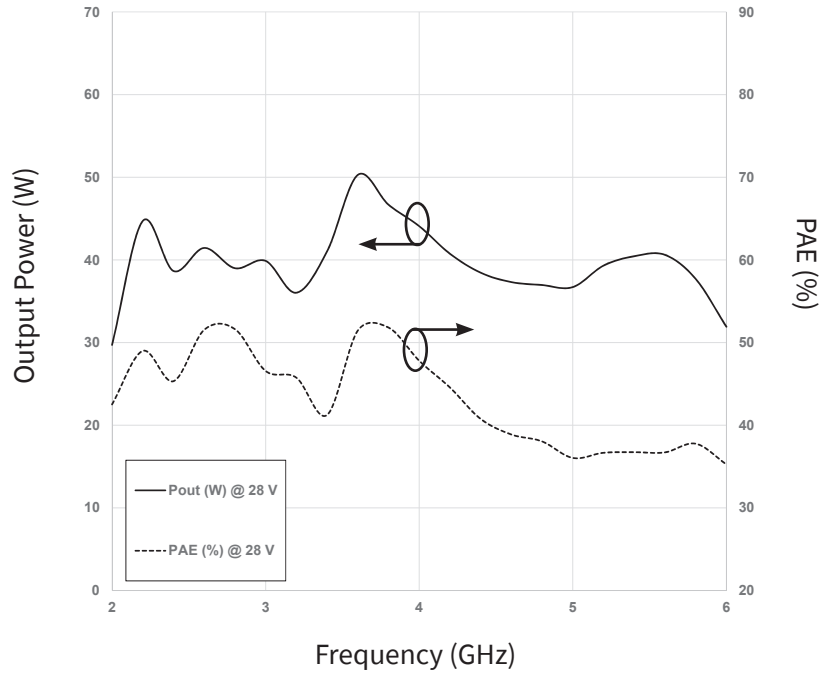
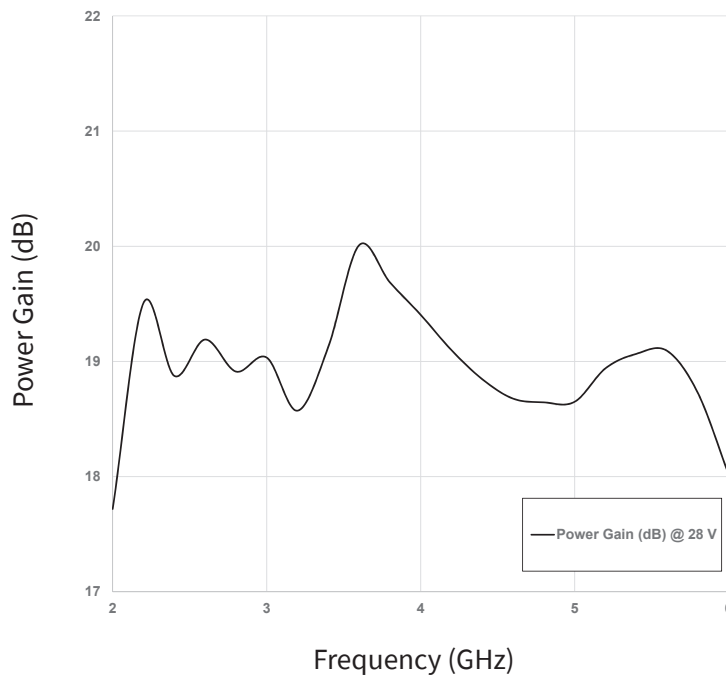


Figure 4. CPA2060035F Power Gain vs. Frequency

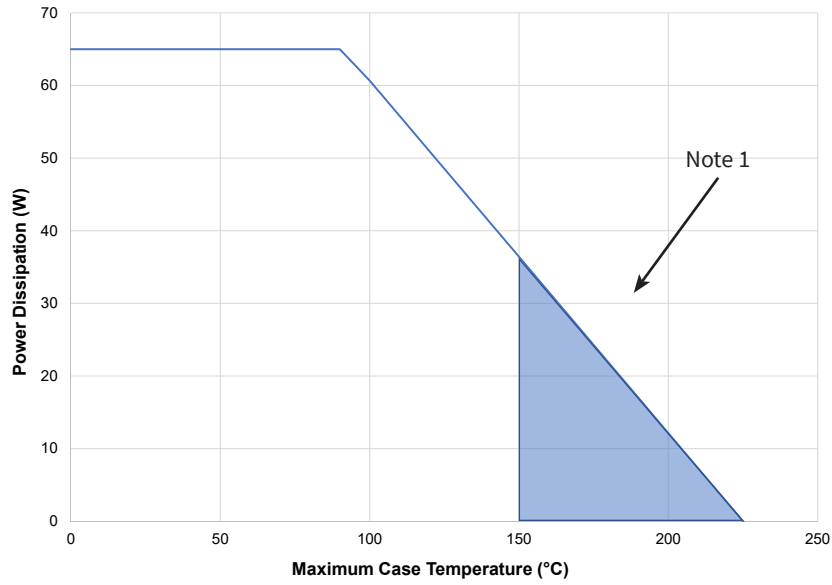
$I_{DQ} = 1.2$ A





Typical Performance

CPA2060035F CW Power Dissipation De-rating Curve



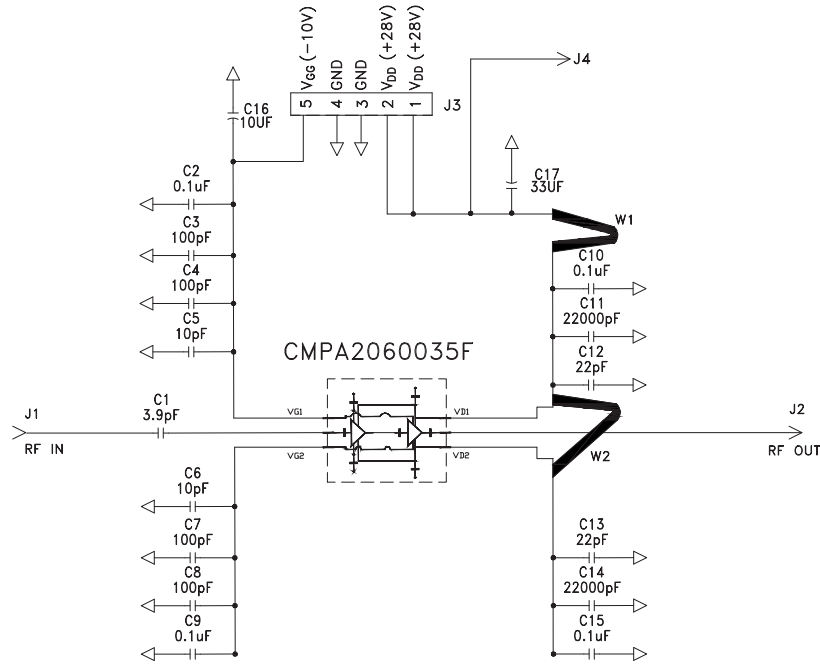
Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).

Electrostatic Discharge (ESD) Classifications

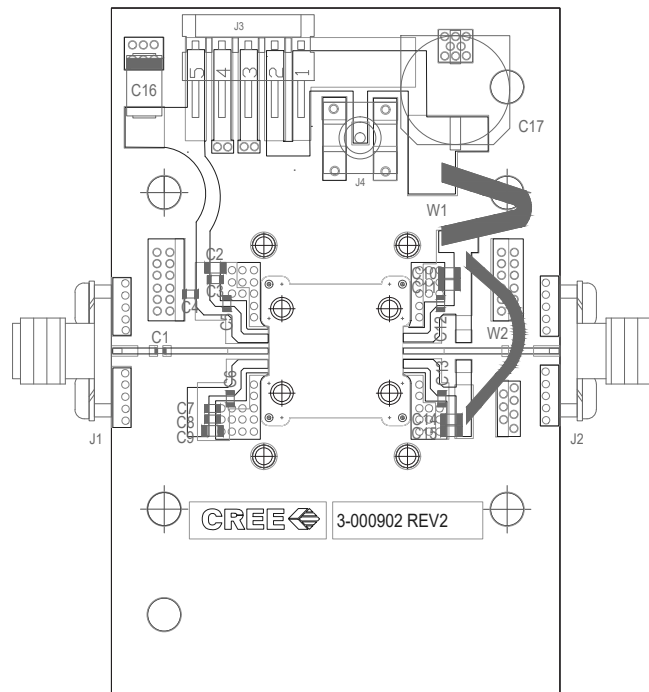
| Parameter | Symbol | Class | Test Methodology |
|---------------------|--------|------------------|---------------------|
| Human Body Model | HBM | 1A (> 250 V) | JEDEC JESD22 A114-D |
| Charge Device Model | CDM | II (200 < 500 V) | JEDEC JESD22 C101-C |



CMPA2060035F-AMP Demonstration Amplifier Circuit Schematic



CMPA2060035F-AMP Demonstration Amplifier Circuit Outline



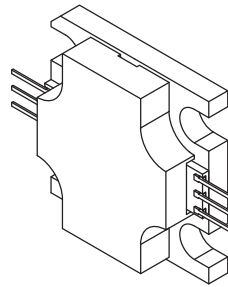
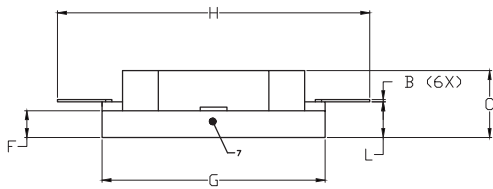
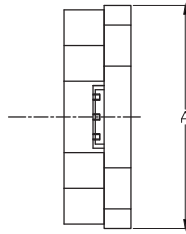
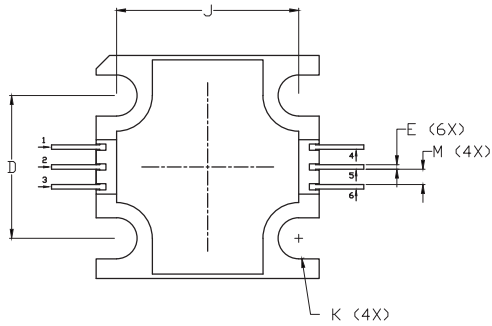


CMPA2060035F-AMP Demonstration Amplifier Circuit Bill of Materials

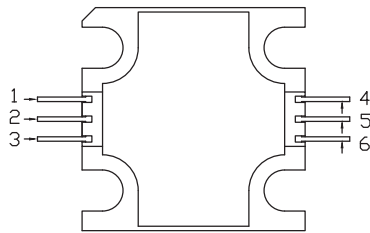
| Designator | Description | Qty |
|------------------|---|-----|
| | PCB | 1 |
| Q1 | CMPA2060035F, 2.0-6.0GHz, GaN MMIC | 1 |
| C1 | CAP, 3.9pF, +/-0.1pF, 0402, ATC | 1 |
| C2, C9, C10, C15 | CAP CER 0.1UF 100V 10% X7R 0805 | 4 |
| C3, C4, C7, C8 | CAP, 100.0pF, +/-5%, 0603, ATC | 4 |
| C5, C6 | CAP, 10.0pF, +/-5%, 0603, ATC | 2 |
| C11, C14 | CAP CER 2200PF 100V 10% X7R 0805 | 2 |
| C12, C13 | CAP, 22pF, +/-5%, 0603, ATC | 2 |
| C16 | CAP 10UF 16V TANTALUM, 2312 | 1 |
| C17 | CAP, 33 UF, 20%, G CASE | 1 |
| J1, J2 | CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL | 2 |
| J3 | HEADER RT>PLZ .1CEN LK 5POS | 1 |
| J4 | CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED | 1 |
| W1, W2 | WIRE, BLACK, 22 AWG | 2 |
| | WIRE ASSEMBLY, 5-PIN, MMIC HPA FIXTURES | 1 |
| | CLAMP, DELRIN | 2 |
| | 2-56 SOC HD SCREW 3/16 SS | 4 |
| | 2-56 SOC HD SCREW 1/2 SS | 4 |
| | PREFORM, INDIUM, 2 X 2 X 0.003" THK, WITH 0.0002" THK AL CLAD ON ONE SIDE | 1 |
| | TEST FIXTURE INSTRUCTIONS | 1 |



Product Dimensions CPM2060035F (Package Type – 440219)



NOT TO SCALE



| PIN | Function |
|-----|----------|
| 1 | Gate 1 |
| 2 | RFIN |
| 3 | Gate 2 |
| 4 | Drain 1 |
| 5 | RFOUT |
| 6 | Drain 2 |
| 7 | Ground |

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE NI/AU

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.495 | 0.505 | 12.57 | 12.82 |
| B | 0.003 | 0.005 | 0.076 | 0.127 |
| C | 0.140 | 0.160 | 3.56 | 4.06 |
| D | 0.315 | 0.325 | 8.00 | 8.25 |
| E | 0.008 | 0.012 | 0.204 | 0.304 |
| F | 0.055 | 0.065 | 1.40 | 1.65 |
| G | 0.495 | 0.505 | 12.57 | 12.82 |
| H | 0.695 | 0.705 | 17.65 | 17.91 |
| J | 0.403 | 0.413 | 10.24 | 10.49 |
| K | Ø .092 | | 2.34 | |
| L | 0.075 | 0.085 | 1.905 | 2.159 |
| M | 0.032 | 0.040 | 0.82 | 1.02 |



Product Ordering Information

| Order Number | Description | Unit of Measure | Image |
|------------------|------------------------------------|-----------------|-------|
| CMPA2060035F | GaN MMIC | Each | |
| CMPA2060035F-AMP | Test board with GaN MMIC installed | Each | |



For more information, please contact:

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Durham, North Carolina, USA 27703
www.wolfspeed.com/rf

Sales Contact
rfsales@cree.com

Notes & Disclaimer

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